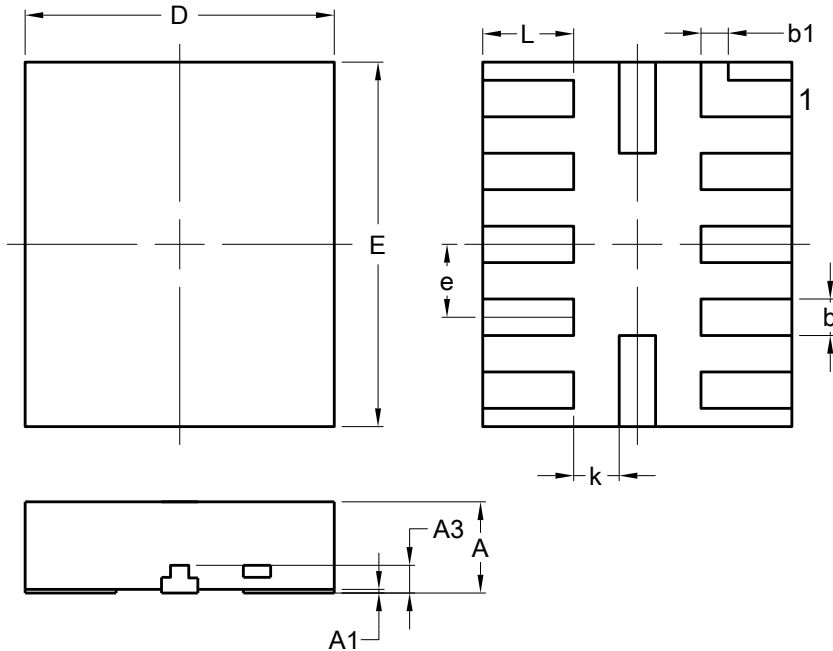


## Package Outline Dimensions

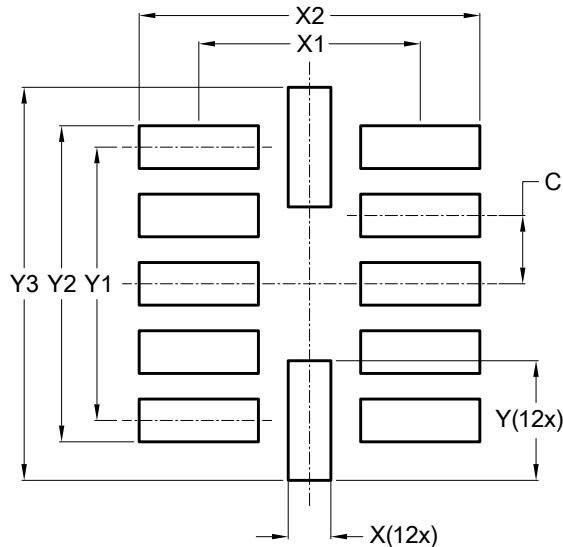
U-QFN1720-12 (Type CJ)



X1-QFN1720-12 (Type CJ)			
Dim	Min	Max	Typ
A	0.450	0.550	--
A1	0.00	0.050	--
A3	0.152 REF		
b	0.150	0.250	--
b1	0.150 REF		
D	1.600	1.800	--
E	1.900	2.100	--
e	0.400 BSC		
k	0.250 REF		
L	0.400	0.600	--
<b>All Dimensions in mm</b>			

## Suggested Pad Layout

U-QFN1720-12 (Type CJ)



Dimensions	Value (in mm)
C	0.400
X	0.250
X1	1.300
X2	2.000
Y	0.700
Y1	1.600
Y2	1.850
Y3	2.300

### ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.